

# Higher integration and intelligence for compact inverter design

IFPS IPC ISD DEV TM  
Sep, 2018



# Agenda

- 1 Intelligent Power Modules
- 2 Infineon CIPOS™ IPM Products
- 3 Applications
- 4 Supporting tools
- 5 New products and features

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# Functional integration on system level is mainstream up to highest power

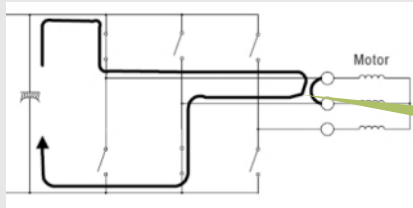


System benefits translate to **customer advantages**  
IPMs improve **time to market, performance** and **reliability**

# Functional integration on system level brings various benefits for our customers

## Over current protection

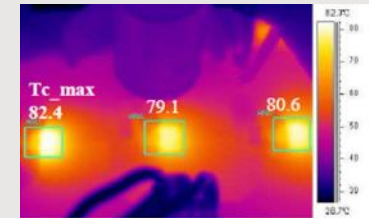
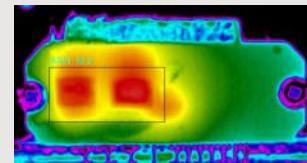
- > IGBT with short circuit rating
- > Integrated protection features



Line-line short

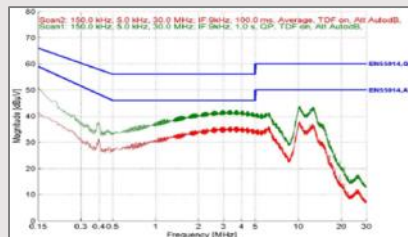
## Temperature feedback & protection

- > Built-in thermistor
- > Correlation between thermistor and IGBT temperatures



## Designed for EMI

- > Optimized trade-off between losses and EMI performance
- > Homogenous dV/dt helps customers design a platform across different power ranges



## Quality

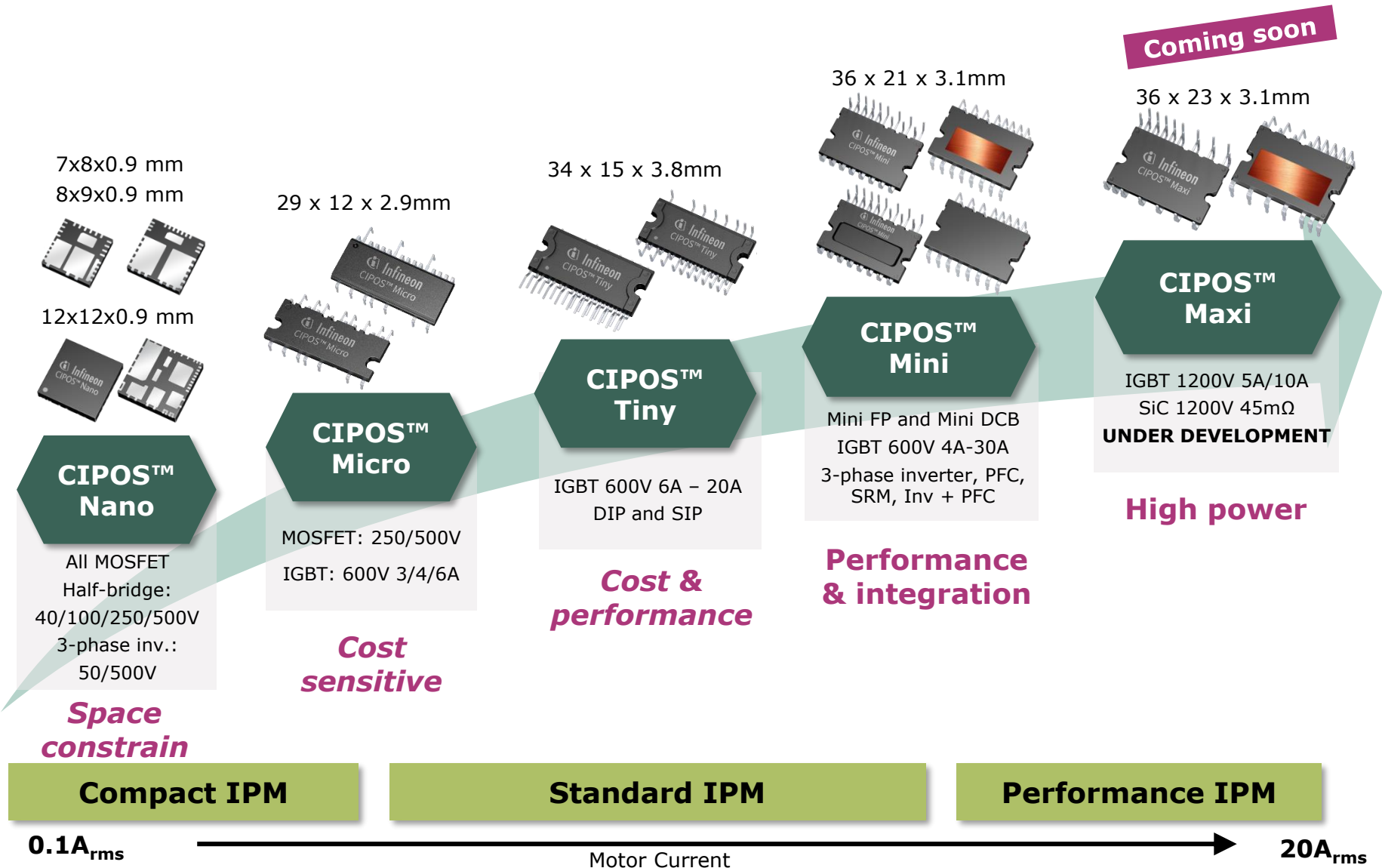
- > Fully qualified by Infineon
- > Meets UL standards



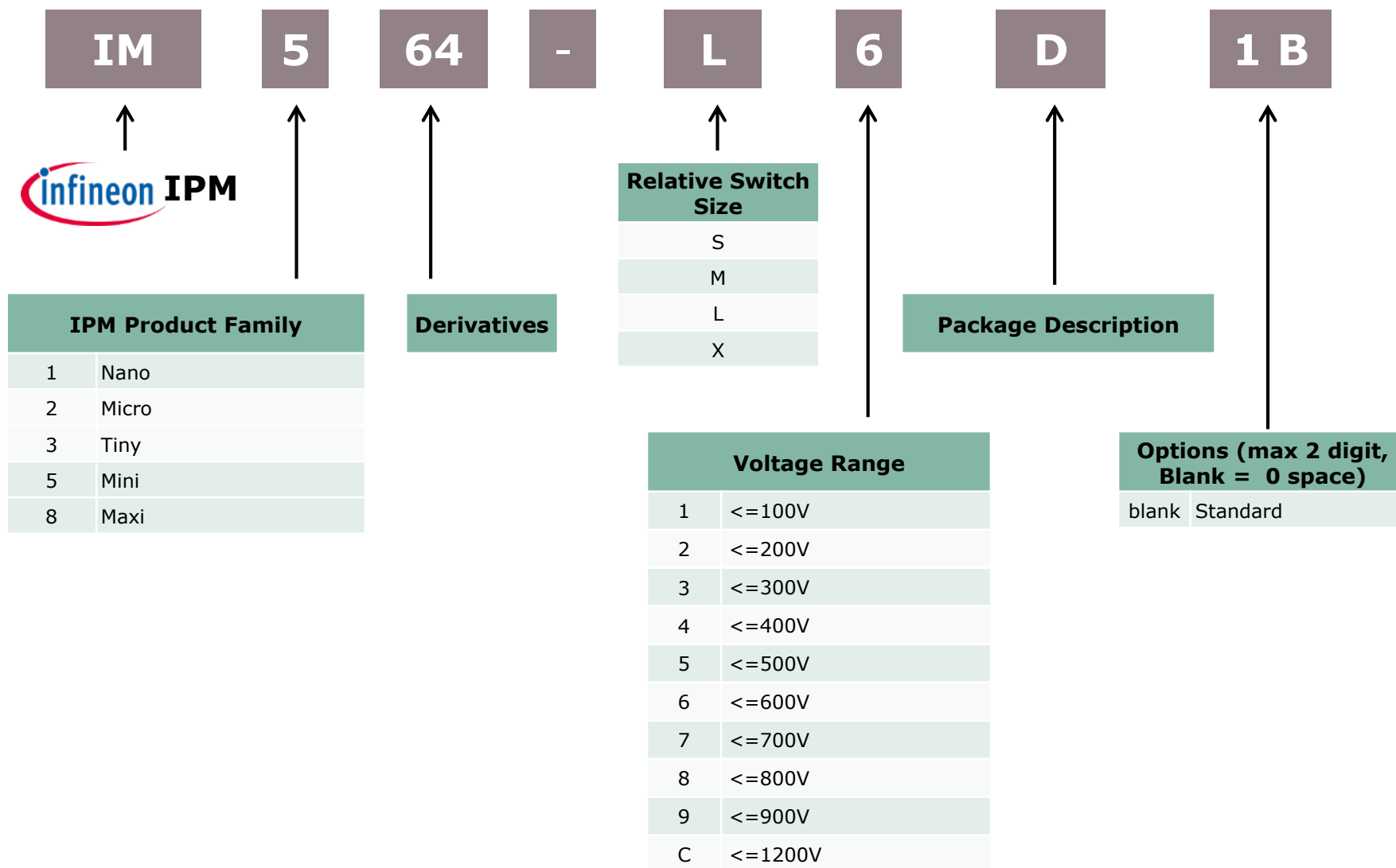
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# Control Integrated Power System (CIPOS™) Product Portfolio



# CIPOS™ IPM nomenclature



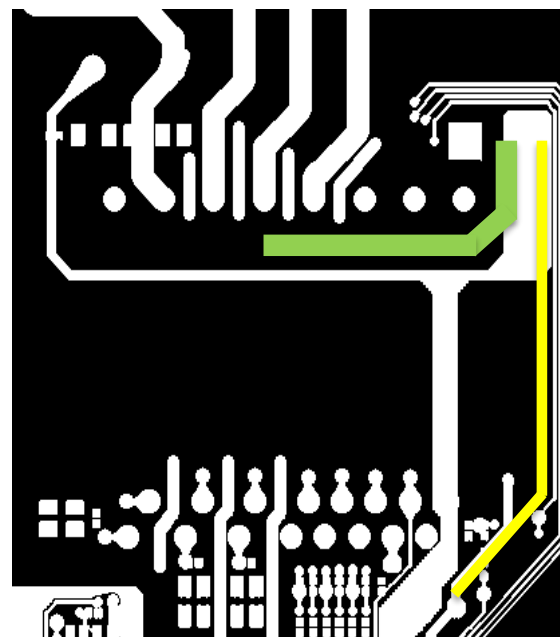


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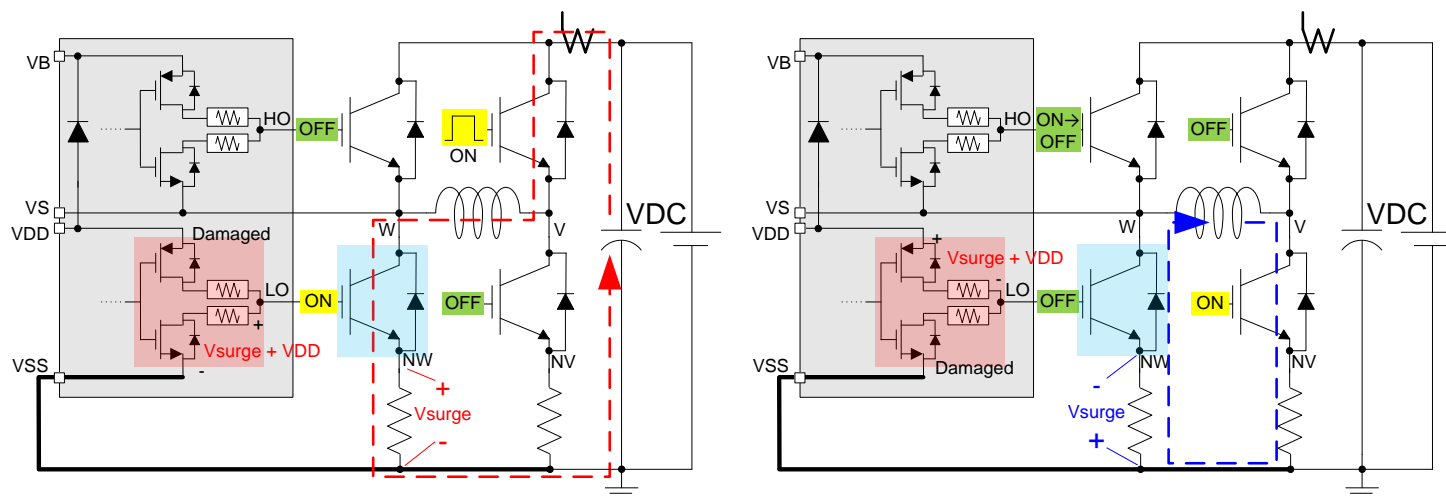


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# IPM damage by N-Vss surge voltage

- ›  $V_{\text{surge}}$  is induced due to parasitic inductance of PCB pattern and shunt resistor when current flows into low-side IGBT or free-wheels through anti-parallel diode.
- ›  $V_{\text{surge}} + V_{\text{DD}}$  is applied to output buffer stage of drive IC.
- › After drive IC has damaged, IGBT could be failed as well.
- › Non-inductive type shunt resistor is recommended.
- › Need to minimize distance between shunt resistor and IPM.



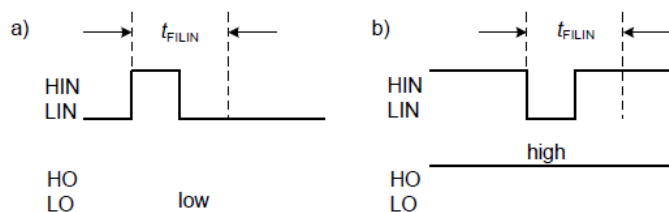
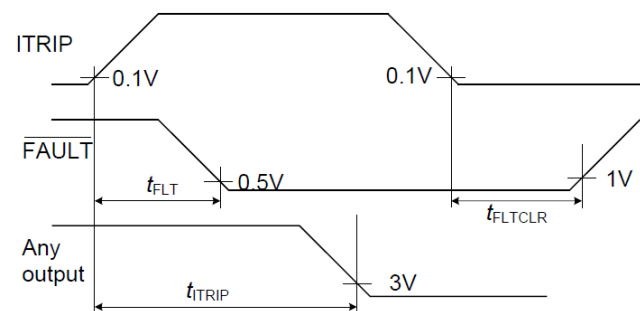
# Considerations from MCU side

## › Fault clear time

- IPM restarts after fault clear time
- Repetitive short circuit conditions should be avoided

## › Input filter time

- PWM input
- Over current



Input filter time ITRIP	$V_{ITRIP} = 1V$	$t_{ITRIPmin}$	-	530	-	ns
Input filter time at LIN, HIN for turn on and off	$V_{LIN, HIN} = 0V \text{ \& } 5V$	$t_{FILIN}$	-	290	-	ns
Input filter time (HIN, LIN, ITRIP)	$T_{FILIN}$	$V_{IN} = 0 \text{ or } V_{IN} = 5V$	-	350	-	ns

Mini

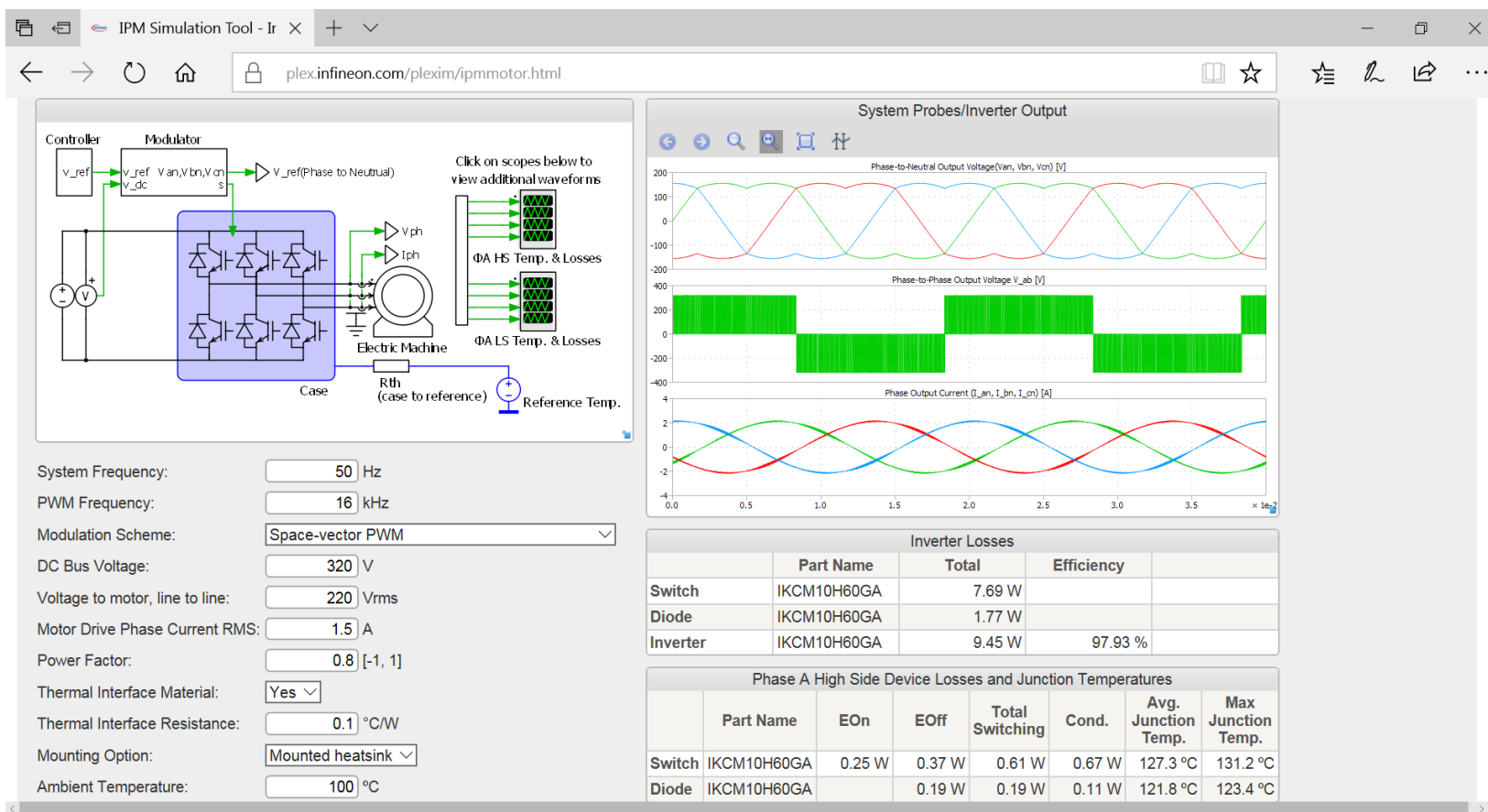
Tiny

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# Simulation Tools

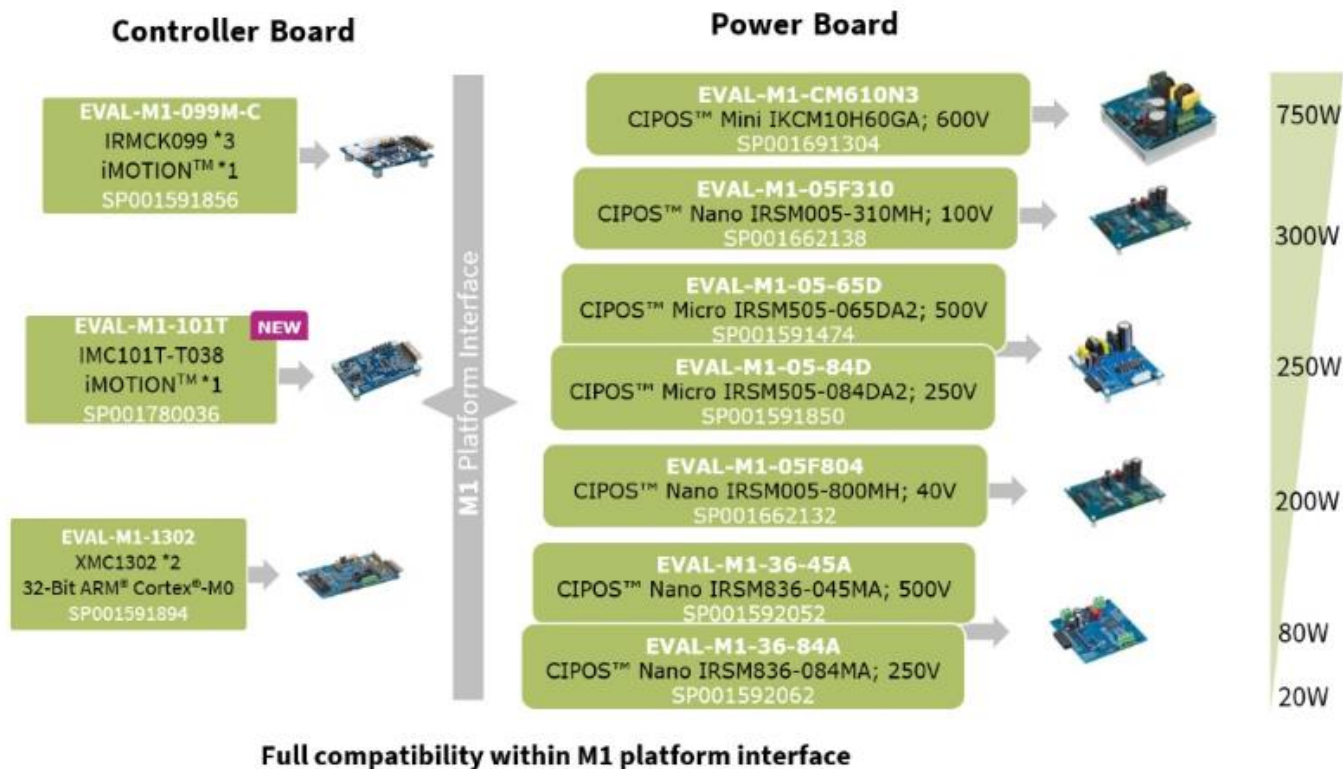
› <https://plex.infineon.com/plexim/ipmmotor.html>



# Reference Designs and Modular Evaluation Boards

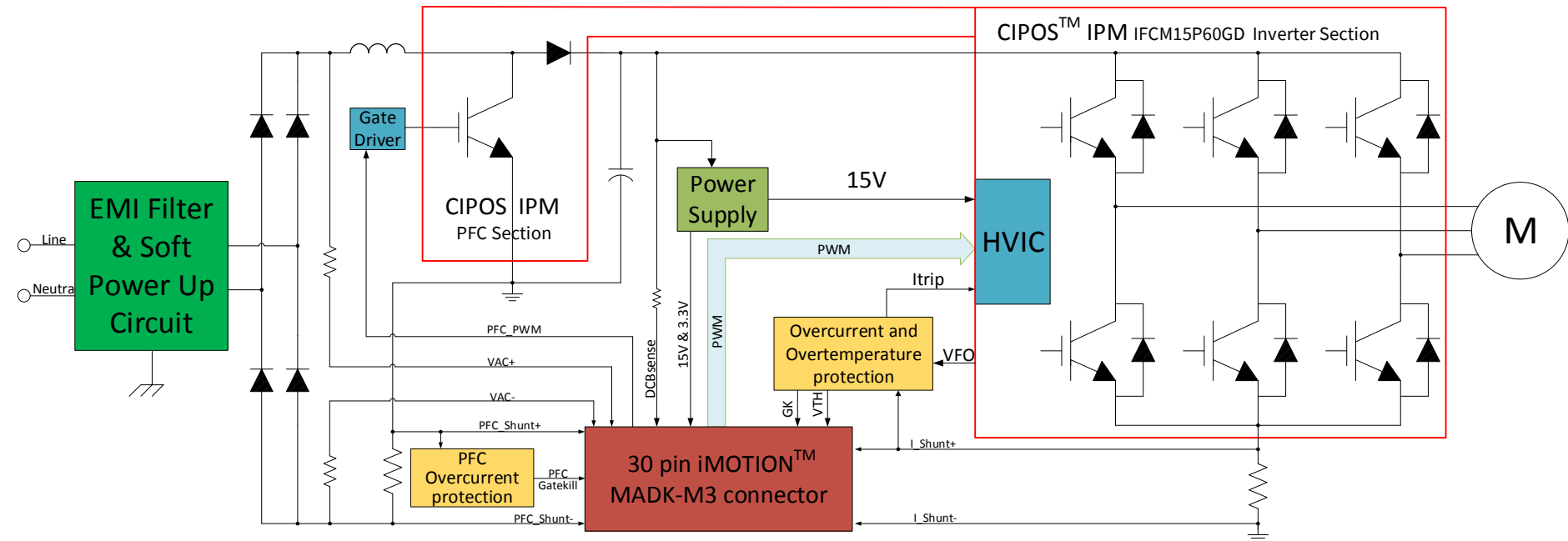
› [www.infineon.com/MADK](http://www.infineon.com/MADK)

Modular approach allows a maximum in flexibility and scalability



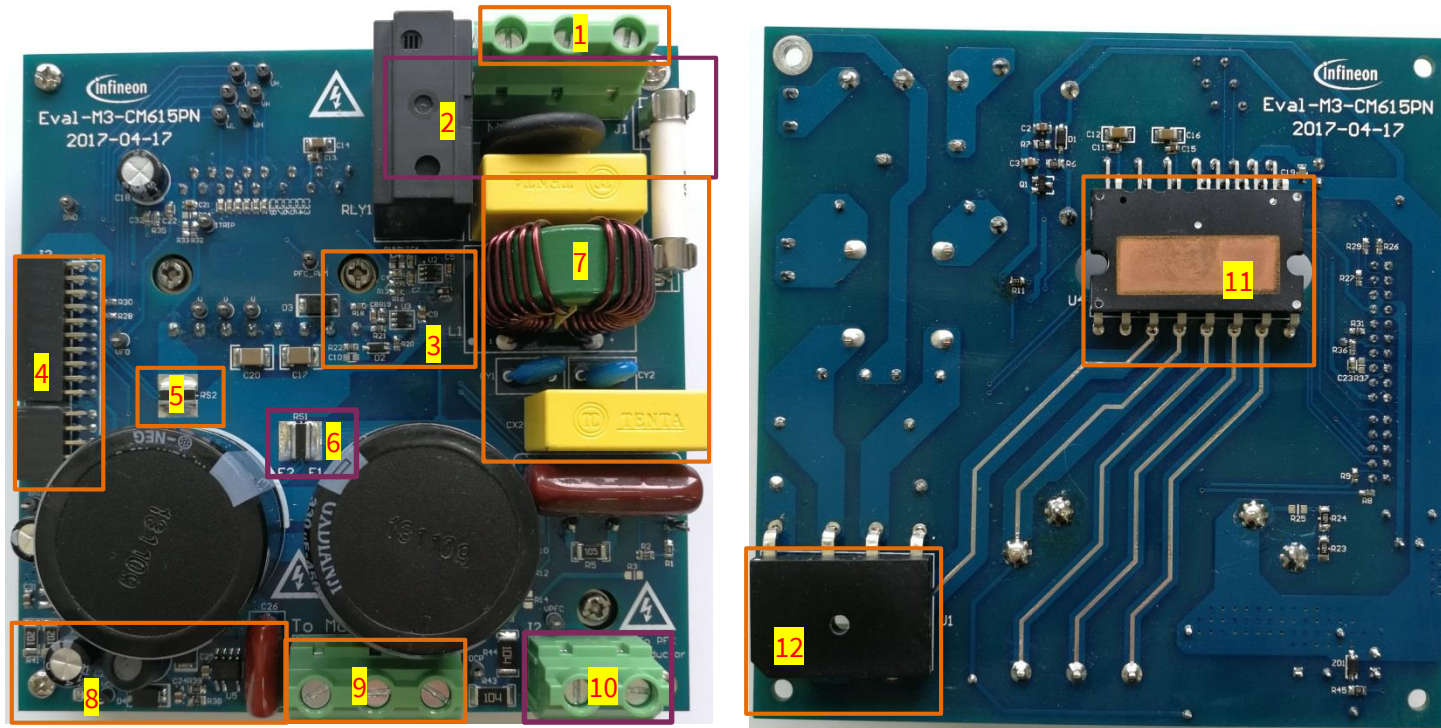


# PFC Integrated IPM : MADK(Modular Application Design Kit) Board



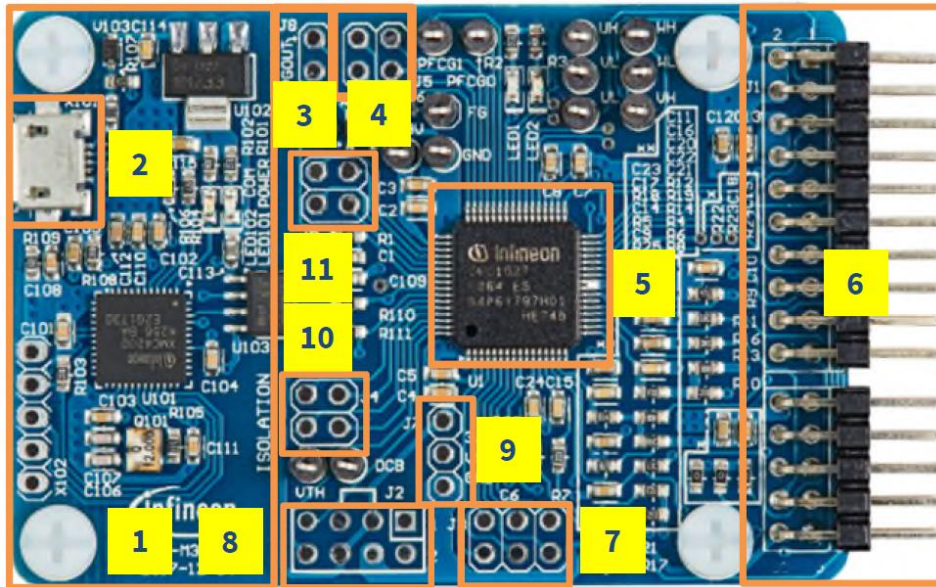
[Block Diagram of eval-M3-CM615PN]

# PFC Integrated IPM : MADK(1) – [Eval-M3-CM615PN]



1. J1 - AC Input connector
2. Relay, NTC and Fuse
3. PFC gate drive and PFC overcurrent protection circuits
4. J3 - 30 pin iMOTION™ MADK-M3 interface connector for controller board
5. Current sensing shunt resistor RS2
6. PFC Current sensing resistor RS1
7. EMI filter
8. Auxiliary power supply
9. J4 - Motor phase connector
10. J2 - PFC inductor connector
11. U4 - CIPOS Mini PFC Integrated IPM(IFCM15P60GD)
12. U1 - Bridge Rectifier

# PFC Integrated IPM : MADK(2) – [Eval-M3-102T]



1. On-board debugger
2. USB Connector (X101)
3. Test Signal Pin Connector (J8)
4. Test Signal Pin Connector (J5)
5. MCE -control IC IMC102-T064
6. iMOTION™ MADK-M3 30 pins interface connector (J1)
7. Test Signal Pin Connector (J3)
8. iMOTION™ Linker connector (J2)
9. VSP Signal Pin Connector (J7)
10. Test Signal Pin Connector (J4)
11. Test Signal Pin Connector (J6)

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# CIPOS™ IPM Upcoming Products

**CIPOS™  
Maxi**

**CIPOS™  
Mini**

**CIPOS™  
Tiny**

**CIPOS™  
Micro**

**CIPOS™  
Nano**

**IFCM series**  
650V 20/30A PFC  
600V 10/15A PFC + 3ph

**IKCM/IGCM series**  
600V 4-30A 3ph

**IRSM506**  
600V 4A 3ph

**IRSM5x5 series**  
250/500V  
4.5mΩ-6.0Ω 3ph

**IRSM8xx series**  
40V-500V  
4.5mΩ-6.0Ω  
Half-bridge/3ph

**New**

**IM51x series**  
600V 0.33Ω 2/3ph  
CoolMOS™ MOSFET

**New**

**IM393 series**  
600V 6-20A 3ph

**\*IM818 series**  
1200V 5/10A 3ph

**\*IM240 series**  
600V 3/4A 3ph

**\*IM231 series**  
600V 4/6A 3ph

**\*Sample Available NOW**

**Released Products**

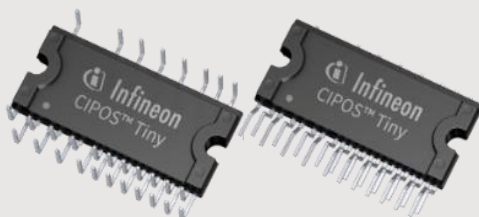
**CY18Q3**

**CY18Q4**

# CIPOS™ Tiny IPM product family

## Products

DIP34x15  
SIP34x15  
package



Dimension [mm]		34x15x3.8		
Configuration		3-phase inverter		
Voltage Rating		600V		
Package		DIP 34x15	SIP 34x15	Lead length options for DIP 5.55/2.9/3.6 mm
Current rating	6A	IM393-S6E	IM393-S6F	
	10A	IM393-M6E	IM393-M6F	
	15A	IM393-L6E	IM393-L6F	
	20A	IM393-X6E	IM393-X6F	

## Features

- › Smallest IPM with current rating up to 20A
- › Newest low  $V_{CE(sat)}$  TRENCHSTOP™ IGBT technology
- › Better EMI performance thanks to new IGBT
- › Under voltage lockout for all channels
- › Cross-conduction prevention logic
- › Integrated bootstrap functionality
- › Built-in NTC thermistor for temperature monitor
- › Offered in both DIP and SIP package with various lead length options

## Typical Applications



## Value Proposition

- › Enables cost reduction for home appliance motor drives
- › SIP option allows PCB size reduction and alternative heatsink mounting
- › UL certified package and temp sensor
- › Improve system efficiency



# CIPOS™ Tiny(IM393)

## : Basic Comparison

Items		CIPOS™ Tiny	CIPOS™ Mini	Competitor A
Package area		32 x 15 mm <sup>2</sup> (100%)	36 x 21 mm <sup>2</sup> (144%)	32.8 x 18.8 mm <sup>2</sup> (117%)
Line up		6A, 10A, 15A, 20A	4A ~ 30A	5A, 15A
Thermistor		Yes	Yes	No (temp. sensor on IC)
Single driver IC benefits		1 driver	1 drivers	2 drivers
Built-in dead time		Typ. 275 [ns]	Typ. 380 [ns]	None
All IGBTs turn off @ protection		All 6 IGBTs	All 6 IGBTs	3 low side IGBT
Anti cross conduction		Yes	Yes	None
Performance comparison		IM393-L6E	IKCM15L60GA	Competitor 15A
IGBT Thermal resistance		Typ. 4.30 [°C/W]	Max. 4.57 [°C/W]	Max. 4.00 [°C/W]
Min. dead time (DT <sub>min</sub> )		1.0 [μs]	1.5 [μs]	1.0 [μs]
IGBT typ. V <sub>CE(sat)</sub> @ I <sub>C</sub> =15A	T <sub>J</sub> =25°C	1.8 [V]	1.8 [V]	1.6 [V]
	T <sub>J</sub> =150°C	2.2 [V]	2.2 [V]	1.8 [V]
V <sub>DC</sub> =300V, V <sub>DD</sub> =15V, I <sub>C</sub> =15A	E <sub>ON</sub> @ T <sub>J</sub> =25 / 150°C	520 / 710 [μJ]	750 / 880 [μJ]	920 / 1170 [μJ]
	E <sub>OFF</sub> @ T <sub>J</sub> =25 / 150°C	270 / 370 [μJ]	290 / 350 [μJ]	170 / 220 [μJ]
	E <sub>rr</sub> @ T <sub>J</sub> =25 / 150°C	78 / 130 [μJ]	34 / 62 [μJ]	210 / 280 [μJ]

# CIPOS™ Micro IPM: IM231 Series

IM231-L6 (600V, 6A)  
IM231-M6 (600V, 4A)

Overcurrent Protection  
( $\pm 5\%$  Accuracy)

Fault Reporting + Auto Fault Clear

Accurate UL Certified NTC

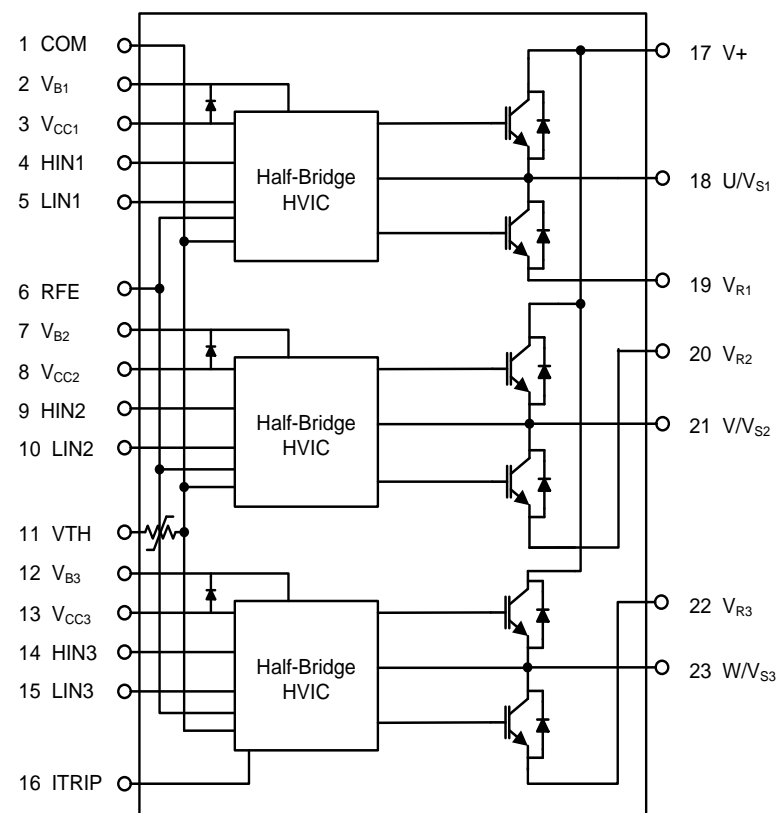
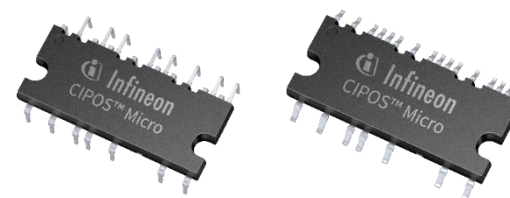
Shoot-Through Protection

Surface Mount & Through Hole  
Options

Mounting Holes

Target Power: Up to  $\sim 450\text{W}$

12 x 29 x 3.2mm





# Ruggedness & Reliability:

## Advanced reliability



IM231 is qualified beyond standard quality specs for higher reliability

IM231-L6 subject to standard Infineon industrial qualification **PLUS:**

**1. High Voltage H3TRB (480V per switch, 85% RH, 85C, 1000h)**

- **PLUS: 125C bake for 24hrs, 30C/60%RH soak for 192hrs, 3x reflow at 245C**
- High reliability with humid environment

**2. Extended Temperature Cycling (TC) to 1500 cycles**

- TC evaluates package reliability including bondwires, die attach.
- Typical TC is run for 1000 cycles only

**3. Extended IOL to 15000 cycles**

- IOL simulates thermal and power stresses during drastic load changes
- IGBT junction temperature changes by 90C within each cycle
- IOL is typically run to 10000 cycles.

# CIPOS™ Maxi IPM: IM818 series

## Key Features

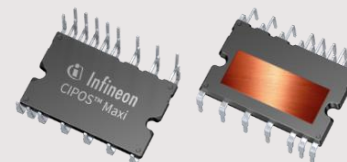
- > Fully isolated Dual In-Line molded module with TRENCHSTOP™ IGBT 4
- > Rugged SOI gate driver technology (6ED)
- > Allowable negative VS potential up to -11V for signal transmission at VBS=15V
- > Integrated bootstrap functionality
- > Over current shutdown
- > Independent temperature Thermistor
- > Under-voltage lockout at all channels
- > Low side emitter pins accessible for all phase current monitoring (open emitter)

## Typical Applications



## Product line-up

Product no.	Voltage Rating	Current Rating	Package
IM818-SCC	1200V	5A	DIP36X23D
IM818-MCC	1200V	10A	DIP36X23D



## Value Proposition

- > System cost saving
- > Time to market
- > High power density with small package

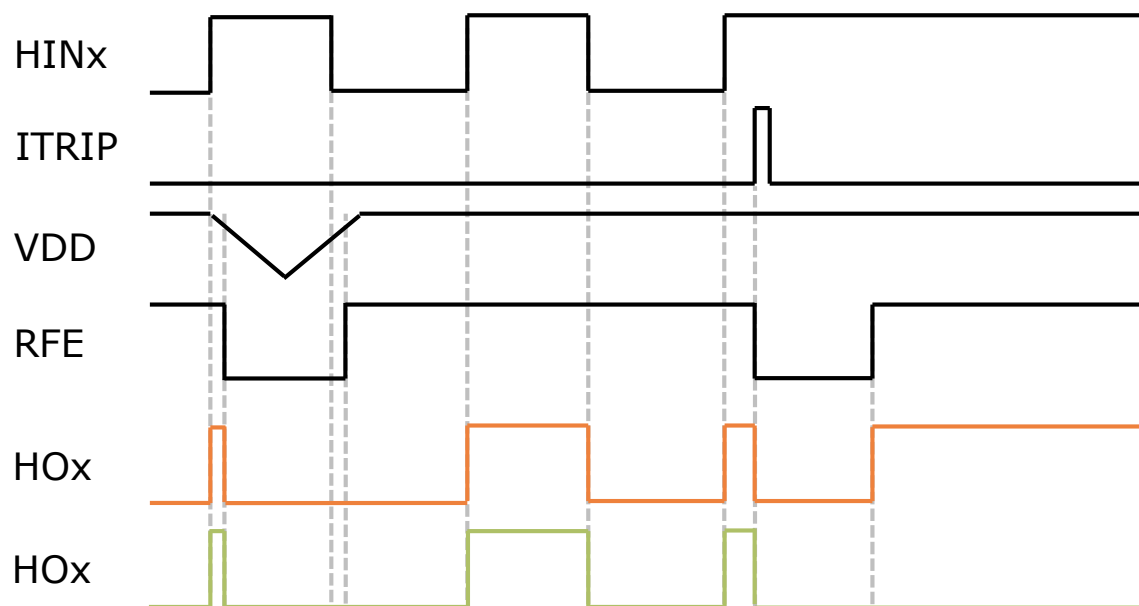
# CIPOS™ Maxi(IM818)

## : Basic Comparison

Items		CIPOS™ Maxi	Competitor A	Competitor B
Package area		36 x 22.7 mm <sup>2</sup> (100%)	52.5 x 31 mm <sup>2</sup> (200%)	44 x 26.8 mm <sup>2</sup> (144%)
Line up		5A, 10A	5A, 10A	10A, 15A, 20A
*Dummy pin(Live)		No	Yes	Yes
Gate Driver IC		Silicon On Insulator	PN junction	PN junction
Single driver IC benefits - Built-in dead time - Anti cross conduction - Matched propagation delay - All IGBTs turn off @ protection		Yes 1 gate driver	No 4 gate drivers (3 for high side, 1 for low side)	No 4 gate drivers (3 for high side, 1 for low side)
Built-in Bootstrap		Yes	Yes	No
Thermistor		Yes	No (temp. sensor on IC)	No (temp. sensor on IC)
Performance comparison		IM818-MCC	Competitor A 10A	Competitor B 10A
IGBT Thermal resistance		Max. 1.85 [°C/W]	Max. 1.50 [°C/W]	Max. 1.80 [°C/W]
IGBT typ. $V_{CE(sat)}$ @ $I_C=10A$	$T_J=25^{\circ}C$	2.1 [V]	1.5 [V]	2.0 [V]
	$T_J=150^{\circ}C$	2.4 [V]	1.6 [V]	2.4 [V]
BVCEs @ $I_{CES}=250 [\mu A]$		1330 / 1400 [V]	1430 / 1502 [V]	1330 / 1214 [V]
Min. dead time(DT <sub>min</sub> )		0.5 [ $\mu s$ ]	3.0 [ $\mu s$ ]	2.0 [ $\mu s$ ]
$V_{DC}=600V$ , $V_{DD}=15V$ , $I_C=10A$	$E_{ON}$ @ $T_J=25 / 150^{\circ}C$	1070 / 1560 [ $\mu J$ ]	1150 / 1860 [ $\mu J$ ]	1260 / 1880 [ $\mu J$ ]
	$E_{OFF}$ @ $T_J=25 / 150^{\circ}C$	560 / 860 [ $\mu J$ ]	740 / 1110 [ $\mu J$ ]	460 / 750 [ $\mu J$ ]
	$E_{rr}$ @ $T_J=25 / 150^{\circ}C$	310 / 670 [ $\mu J$ ]	370 / 810 [ $\mu J$ ]	300 / 610 [ $\mu J$ ]

# Sleep function

- › Sleep function is activated after each trigger of ITRIP or UVLO.
- › A new edge of LIN and HIN is required for LO or HO after release of fault out.





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